

Electronic Patent Application Fee Transmittal

Application Number:	10550153
Filing Date:	20-Sep-2005
Title of Invention:	Method for Analyzing Copper Electroplating Solution, Apparatus for the Analysis, and Method for Fabricating Semiconductor Product
First Named Inventor/Applicant Name:	Toshikazu Okubo
Filer:	Cameron Kerrigan/Mary Padilla
Attorney Docket Number:	038915.00045

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Independent claims in excess of 3	1614	4	220	880

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Extension-of-Time:

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				880